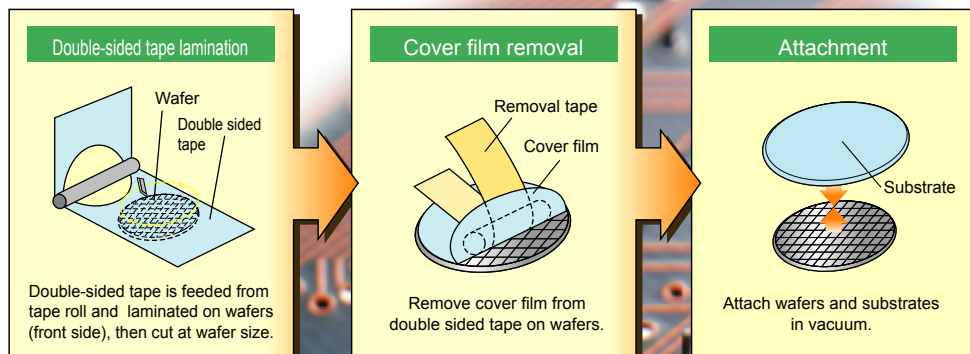


MODEL WSM-100

WAFER/SUBSTRATE ATTACHING MACHINE

Outline

This machine laminates double-sided tape onto wafers, remove cover film on it, and attaches wafers and substrates. Attachment of wafers and substrates is made in Takatori unique vacuum chamber. So the laminating without air bubbles and with uniform attaching pressure is available.



Specification	WSM-100
Throughput	40wafer/h
Wafer Size	6 inch, 8 inch
Dimensions	D1,760 × W1,700 × H1,800mm
Weight	850kg

System appearance and specifications are subject to change without prior notice from the supplier.

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